Title (en)

CHIP ELEMENTS MOUNTED ON WIRES HAVING AN INCIPIENT BREAKING POINT

Title (de)

AUF DRÄHTEN MONTIERTE CHIPELEMENTE MIT EINEM ANBRUCHPUNKT

Title (fr)

ELEMENTS A PUCE ASSEMBLES SUR DES FILS PRESENTANT UNE AMORCE DE RUPTURE

Publication

EP 2586056 A1 20130501 (FR)

Application

EP 11743255 A 20110623

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Abstract (en)

[origin: WO2011161337A1] The invention relates to a chain comprising multiple microelectronic chip elements (10) that are rigidly connected to a wire (12a). The wire has notches (18a) that define preferred breaking points when the wire is subject to tensile stress. If the wire is a conductor, the notches (18a) can be spread in such a way that the length of the wire between a chip element and a notch is equal to the length of an antenna.

IPC 8 full level

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CPC (source: EP US)

B29C 48/05 (2019.01 - EP US); **B29C 48/08** (2019.01 - EP US); **B29C 48/157** (2019.01 - EP US); **G06K 19/07718** (2013.01 - EP US); **G06K 19/07749** (2013.01 - EP US); **G06K 19/07758** (2013.01 - EP US); **G06K 19/07786** (2013.01 - EP US); **H01L 24/48** (2013.01 - EP US); **H01L 24/85** (2013.01 - EP US); **H01L 25/0655** (2013.01 - EP US); **H01L 25/50** (2013.01 - EP US); **H05K 7/02** (2013.01 - US); **H05K 13/00** (2013.01 - US); B29C 48/15 (2019.01 - EP US); B29L 2017/00 (2013.01 - EP US); H01L 2223/6677 (2013.01 - EP US); H01L 2224/05599 (2013.01 - EP US); H01L 2224/451 (2013.01 - EP US); H01L 2224/48 (2013.01 - EP US); H01L 2224/85 (2013.01 - EP US); H01L 2224/85399 (2013.01 - EP US); H01L 2924/00014 (2013.01 - EP US); H01L 2924/01005 (2013.01 - EP US); H01L 2924/01058 (2013.01 - EP US); Y10T 29/49002 (2015.01 - EP US)

Citation (search report)

See references of WO 2011161337A1

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